SEMICONDUCTOR DEVICE

ABSTRACT OF THE DISCLOSURE

Disclosed is a semiconductor device including: a semiconductor element having electrodes; a film circuit having a plurality of external electrodes and lead wirings for connecting the external electrodes to the electrodes of the semiconductor element; a radiating member including a heat spreader for promoting radiation of the semiconductor element from a bottom surface thereof and a reinforcing body disposed in such a manner as to surround the semiconductor element for reinforcing the film circuit, the reinforcing body being formed integrally with the heat spreader; and vent holes formed in the radiating member in such a manner as to communicate gaps between the radiating member and the semiconductor element to an external surface of the radiating member; wherein the lead wirings of the film circuit are bonded to the electrodes of the semiconductor element; connecting portions between the semiconductor element and the film circuit are sealed; and the heat spreader portion is adhesively bonded on the bottom surface of the semiconductor element and the reinforcing body portion is adhesively bonded on a bottom surface of the film circuit.

Figure 5

THIS SHEET HAS BEEN REPLACED

This Sheet Has Been Replaced

